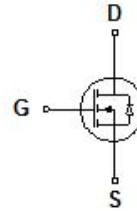


PRELIMINARY DATASHEET

**600V 2X47A, Parallel N-Channel Enhancement Mode
CoolMOS™ Power MOSFET in Extended TO247 Package**

APPLICATIONS

- PC power supplies
- Consumer SMPS
- Telecom power supplies
- Server power supplies
- Solar inverter
- Welding inverter



FEATURES

- Low gate charge
- Ultra low $R_{ds(on)}$ < 0.035Ω
- High dv/dt capability
- High peak current capability
- Pb-free finished; **RoHS compliant**

MAXIMUM RATINGS, $T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Units
Drain - Source Voltage	V_{DSS}	600	V
Drain current – continuous current $T_c = 25^\circ\text{C}$	I_D	75 ²⁾	
$T_c = 100^\circ\text{C}$		60	A
Drain current – pulsed ¹⁾	I_{DM}	282	
Continuous drain-source diode current	I_{SD}	75 ²⁾	
Pulse drain-source diode current	I_{SM}	282	
Gate-source voltage	V_{GSS}	± 30	V
MOSFET dv/dt ruggedness $V_{DS} = 0..480\text{V}$, $I_D = 78\text{A}$	dV/dt	50	V/ns
Operating junction and storage temperature	T_j, T_{stg}	-55... +150	°C

Thermal Characteristics

Parameter	Symbol	Max. Value	Units
Characteristics			
Thermal resistance, junction to case	R_{thJC}	0.15	°C /W
Thermal resistance, junction to ambient	R_{thJA}	62	

ELECTRICAL CHARACTERISTICS, at $T_c = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS} = 0\text{V}$, $I_D = 0.5\text{mA}$	600	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 5.4\text{mA}$	2.1	3.0	3.9	
Drain-source diode forward voltage	V_{SD}	$V_{GS} = 0\text{V}$, $I_{SD} = 94\text{ A}$	-	1.0	1.2	V
Zero gate voltage drain current	I_{DSS}	$V_{GS} = 0\text{V}$, $V_{DS} = 600\text{V}$	-	1	50	μA

Gate-body leakage current, forward	I _{GSS}	V _{GS} = ±30V, V _{DS} = 0V	-	-	±200	nA
Static drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 60 A	-	0.03	0.035	Ω

Dynamic Characteristics

Input capacitance	C _{iss}	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz	-	13600	-	pF
Output capacitance	C _{oss}		-	4400	-	
Reverse transfer capacitance	C _{rss}		-	290	-	

SWITCHING CHARACTERISTICS, at T_c = 25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Turn-on delay time	t _{d(on)}	V _{DS} = 380V, I _D = 94 A, V _{GS} = 0/13V R _G = 1.8 Ω T _j = 125 °C	-	18	-	ns
Rise time	t _r		-	27	-	
Turn-off delay time	t _{d(off)}		-	111	-	
Fall time	t _f		-	8	-	
Gate charge	Q _g	V _{DD} = 350V, I _D = 94 A V _{GS} = 0 to 10V	-	252	-	nC

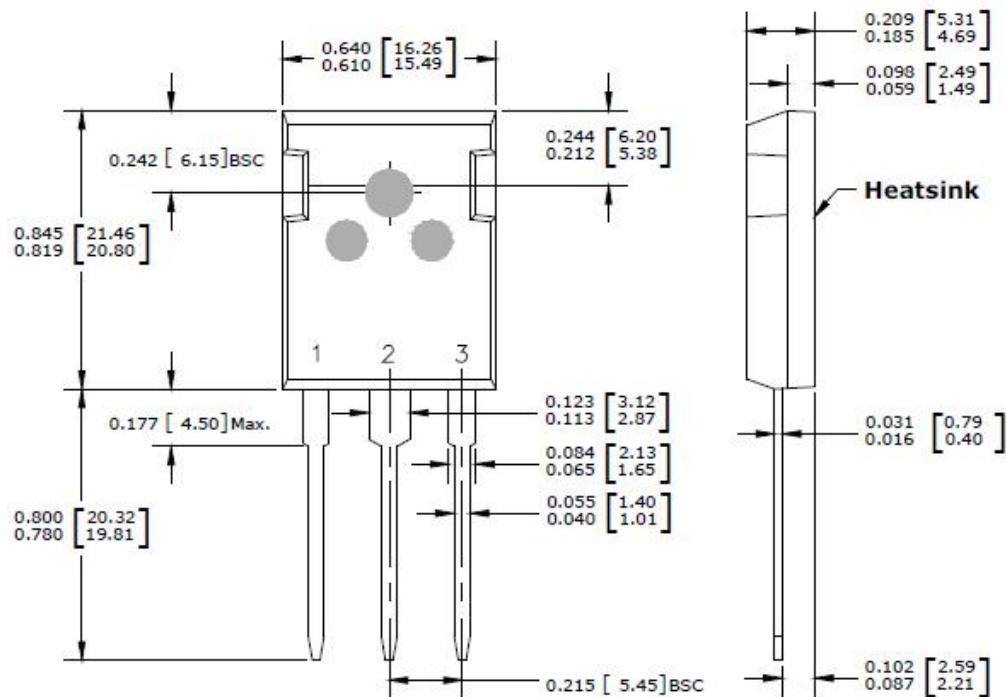
Drain-Source Diode Characteristics, at T_c = 25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Reverse recovery time	t _{rr}	V _{GS} = 0V, I _{SD} = 94A di/dt = 100A/μs	-	580	-	ns
Reverse recovery charge	Q _{rr}		-	46	-	μC
Peak reverse recovery current	I _{rrm}		-	146	-	A

Notes:

1. Repetitive rating: pulse width limited by maximum junction temperature.
2. Lead current limitation

Package Outline Drawing



CoolMOS™ is a registered trademark of Infineon Technologies AG.

CAUTION: These devices are ESD sensitive. Use proper handling procedure.

Disclaimer

These specifications may not be considered as a guarantee of components characteristics. Components have to be tested depending on intended application as adjustments may be necessary. The use of **iQXPRZ Power Inc.** components in life support appliances and systems are subject to written approval of **iQXPRZ Power Inc.**